

ABSTRACT OF THE INVENTION

An integrated heat dissipation apparatus, having a first heat dissipating element, a second heat dissipating element, a thermal conductive heat sink and at least one L-shape heat pipe. The thermal conductive heat sink has a
5 connecting surface and a thermal conductive surface opposing the connecting surface. The first heat dissipating element is mounted on the thermal conductive surface. A plurality of thermal conductors with thermal conductivity larger than that of the thermal conductive heat sink are mounted to the connecting surface. The L-shape heat pipe has two ends, including one
10 end serial connecting to the second heat dissipating element, and the other end extending to connect with the thermal conductors on the thermal conductive heat sink.